

- NOTE) 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX  
 2. CONTACT PLATING SPECIFICATIONS.  
 CONTACT AREA : GOLD 0.05 μm MIN  
 SMT LEAD : GOLD 0.05 μm MIN  
 UNDERPLATING : NICKEL 1 μm MIN  
 ( SURFACE : SEALING )  
 3. EACH CONTACTS AT 4 CORNERS ARE PROVIDED FOR METAL FITTINGS AND GROUNDING PURPOSE.  
 4. HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.  
 5. GATE POSITION IS INDICATED IN APPROX POSITION SHOWN.

PART No.	CODE No.	B	C
BM14B(0.8)-20DS-0.4V(52)	CL684-8004-8-52	6.48	4.4
BM14B(0.8)-22DS-0.4V(52)	CL684-8048-3-52	6.88	4.8
BM14B(0.8)-24DS-0.4V(52)	CL684-8005-0-52	7.28	5.2
BM14B(0.8)-30DS-0.4V(52)	CL684-8006-3-52	8.48	6.4
BM14B(0.8)-34DS-0.4V(52)	CL684-8007-6-52	9.28	7.2
BM14B(0.8)-40DS-0.4V(52)	CL684-8008-9-52	10.48	8.4
BM14B(0.8)-50DS-0.4V(52)	CL684-8009-1-52	12.48	10.4

NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
3	PS	CLEAR (ENBOSSED CARRIER TAPE)	7	POLYIMIDE	BROWN(HEAT RESISTANCE TAPE)
2	PHOSPHOR BRONZE	2	6	PS	CLEAR(REINFORCEMENT COLLAR)
1	LCP	UL94 V-0. BLACK	5	PS	BLACK(PLASTIC REEL)
			4	POLYESTER	CLEAR(COVER TAPE)

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	10:1	1	DIS-H-005892	YN. SAKAMOTO	AR. TAKAHASHI	11.06.13

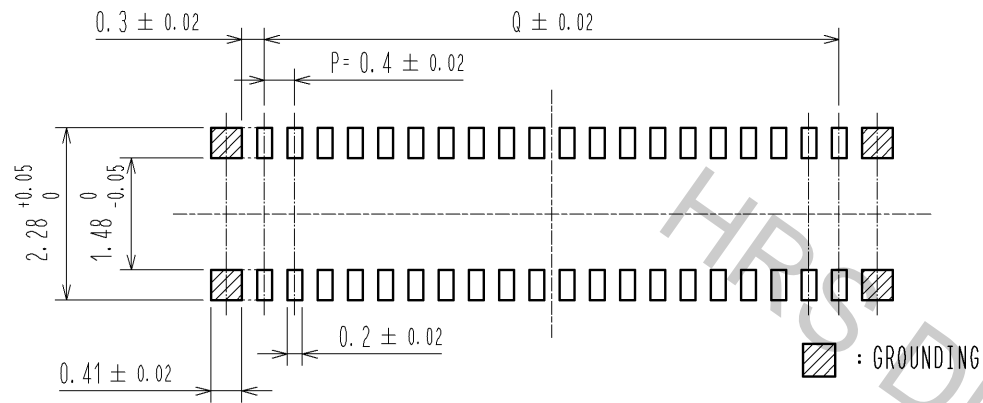
APPROVED	DATE	DRAWING NO.
KH. IKEDA	11.06.09	EDC3-322327-01
AR. TAKAHASHI	11.06.08	
SH. HOSODA	11.06.08	
KR. AJITO	11.06.07	

PART NO.	CODE NO.
BM14B(0.8)-*DS-0.4V(52)	CL684

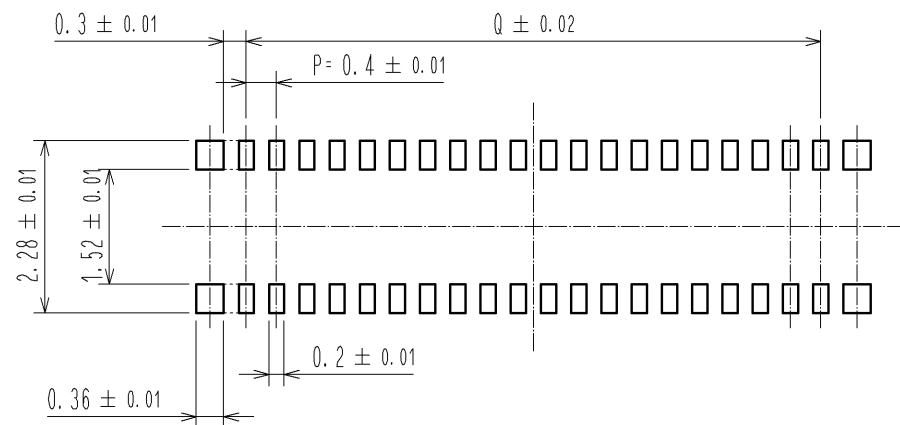
6) RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.

◆ RECOMMENDED PCB LAYOUT

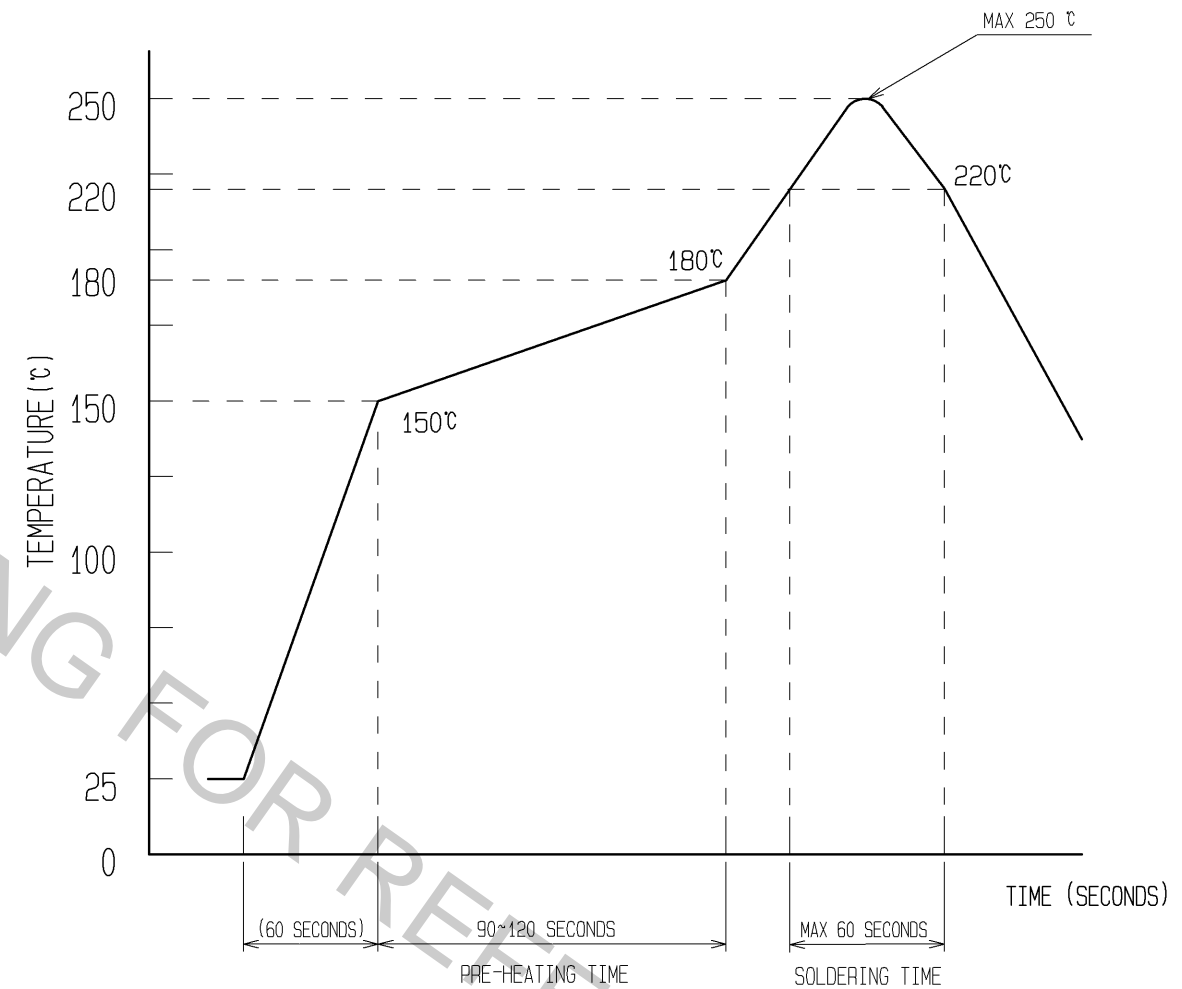


◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μm



PART No.	Q
BM14B(0.8)-20DS-0.4V(52)	3.6
BM14B(0.8)-22DS-0.4V(52)	4.0
BM14B(0.8)-24DS-0.4V(52)	4.4
BM14B(0.8)-30DS-0.4V(52)	5.6
BM14B(0.8)-34DS-0.4V(52)	6.4
BM14B(0.8)-40DS-0.4V(52)	7.6
BM14B(0.8)-50DS-0.4V(52)	9.6



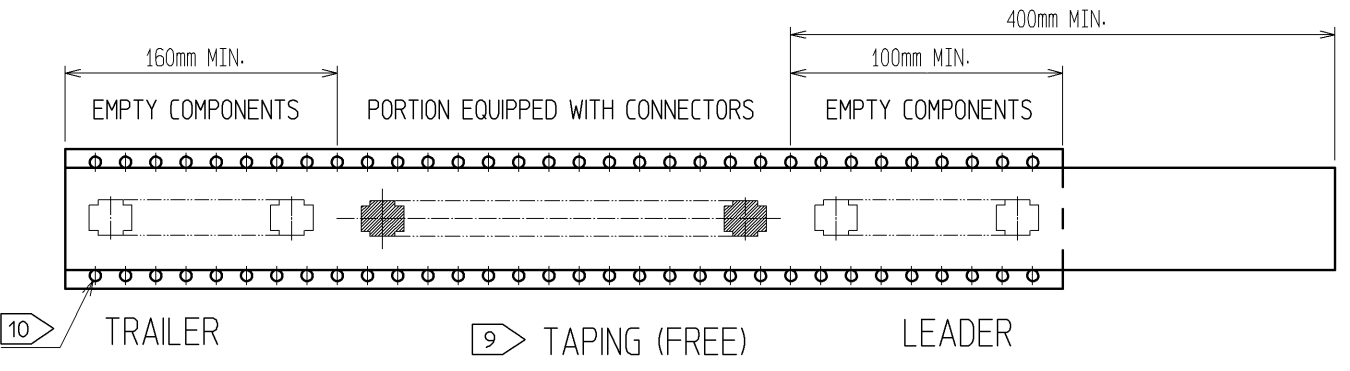
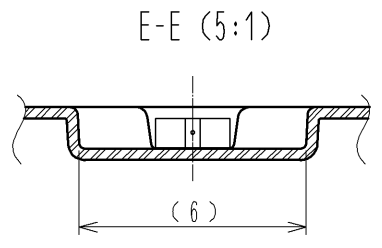
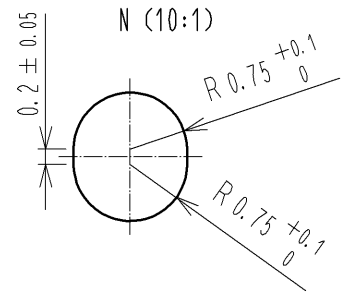
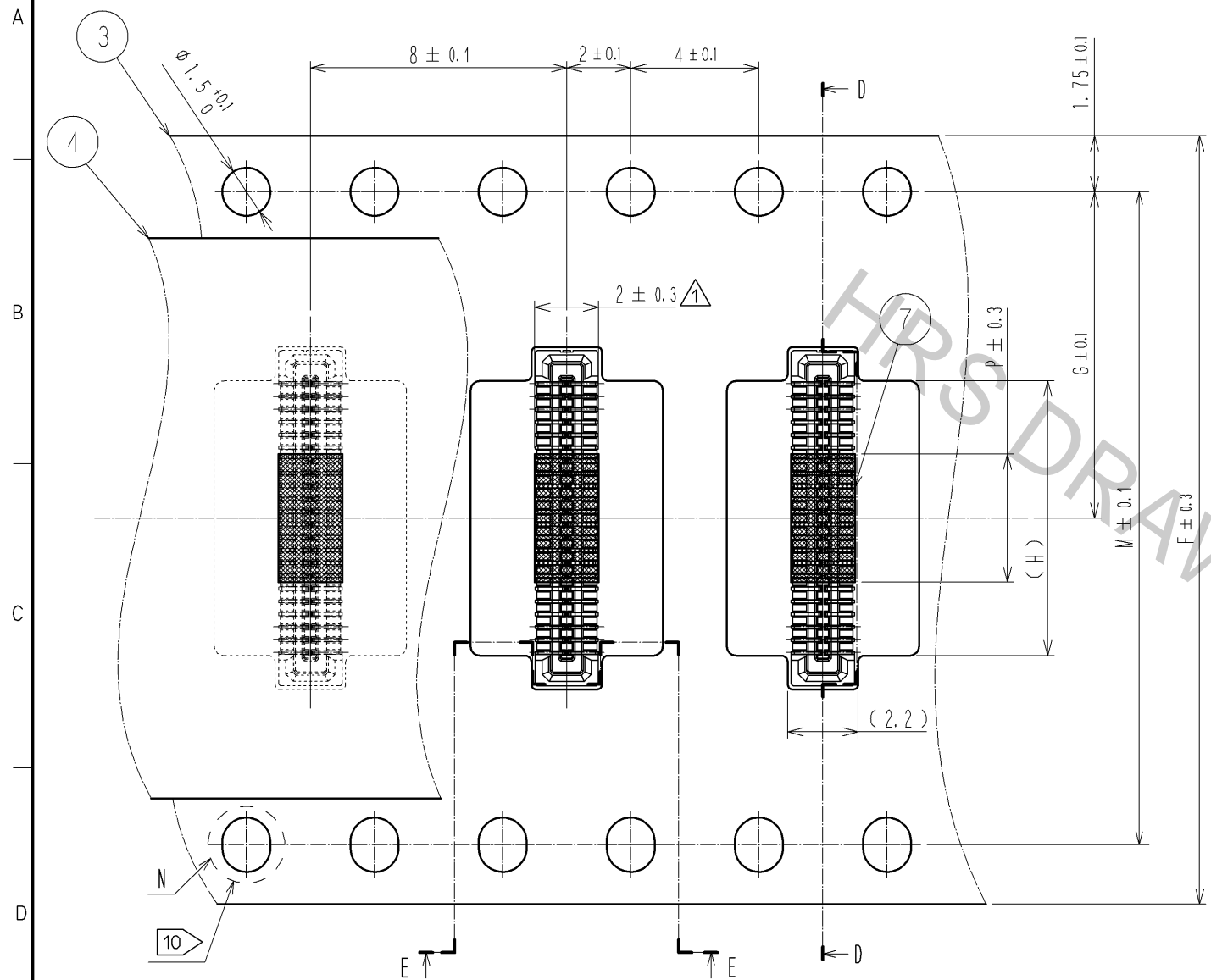
REFLOW METHOD: IR REFLOW  
 NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

- 1) REFLOW TIME  
 DURATION ABOVE 220°C, 60 SEC. MAX.  
 (PEAK TEMPERATURE: 250°C MAX)
- 2) PRE-HEAT TIME  
 PRE-HEAT TEMPERATURE(MIN): 150°C  
 PRE-HEAT TEMPERATURE(MAX): 180°C  
 PRE-HEAT TIME: 90-120 sec.

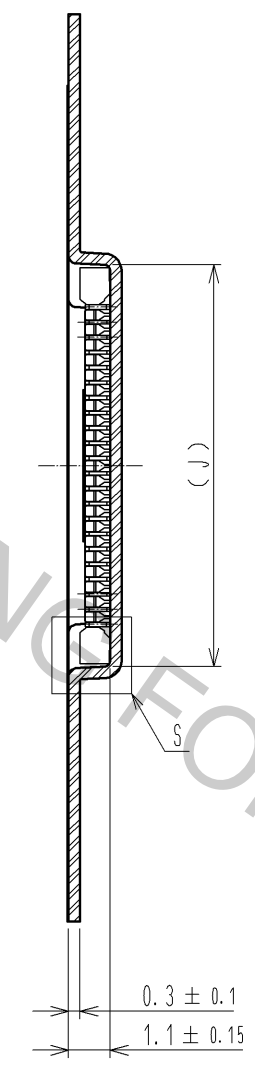
6) THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

<b>HRS</b>	DRAWING NO.	EDC3-322327-01
	PART NO.	BM14B(0.8)-*DS-0.4V(52)
	CODE NO.	CL684
		2/3

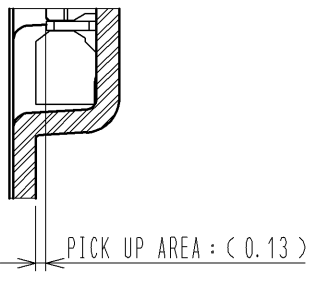
### EMBOSSED CARRIER TAPE PACKAGING (5:1)



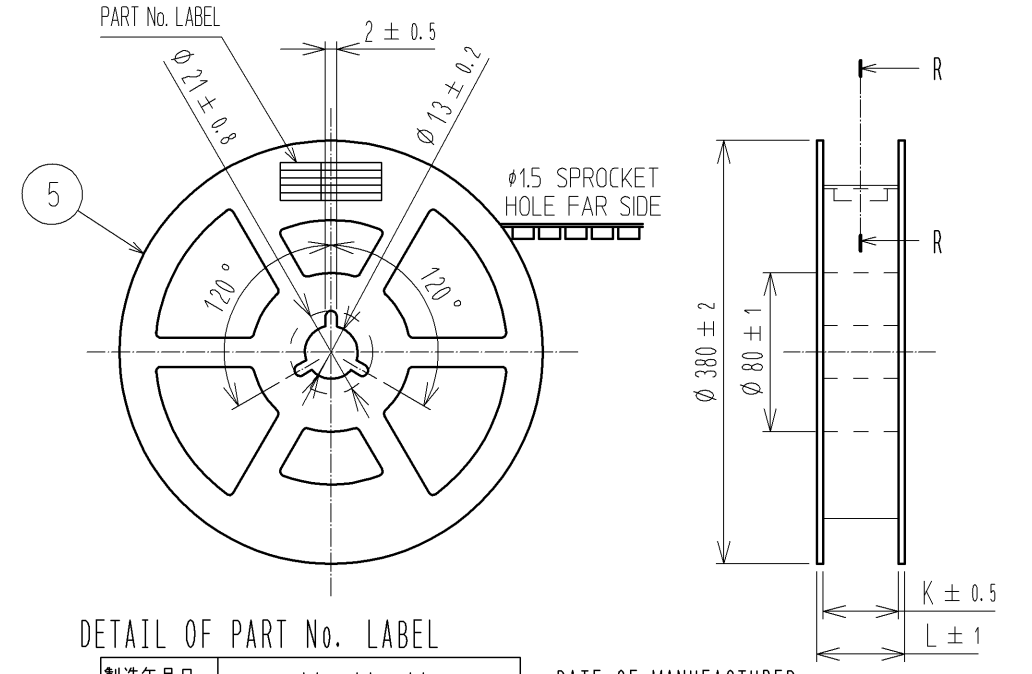
### D-D (5:1)



### S(10:1)



### STYLE AND DIMENTION OF REEL (FREE)

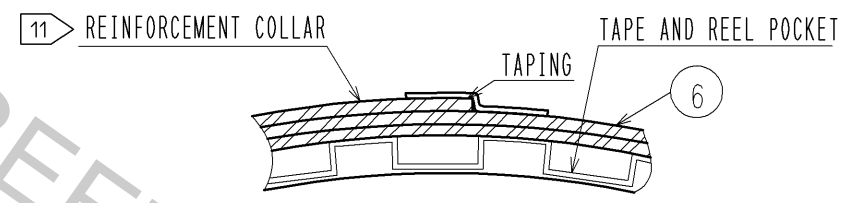


### DETAIL OF PART No. LABEL

製造年月日	** ** *
製品コード	CL0684-****-**-(**)
製品名	BM14B(0.8)-*DS-0.4V(52)
数量	8,000
納入者	ヒロセ電機(株)

DATE OF MANUFACTURED  
CODE No.  
PART No.  
QUANTITY  
SUPPLIER

### R-R (FREE)



PART No.	F	G	H	J	K	L	M	P
BM14B(0.8)-20DS-0.4V(52)	16	7.5	4.58	6.7	17.5	21.5	—	2.98
BM14B(0.8)-22DS-0.4V(52)	16	7.5	4.98	7.1	17.5	21.5	—	2.98
BM14B(0.8)-24DS-0.4V(52)	16	7.5	5.38	7.5	17.5	21.5	—	2.98
BM14B(0.8)-30DS-0.4V(52)	24	11.5	6.58	8.7	25.5	29.5	—	3.98
BM14B(0.8)-34DS-0.4V(52)	24	11.5	7.38	9.5	25.5	29.5	—	3.98
BM14B(0.8)-40DS-0.4V(52)	24	11.5	8.58	10.7	25.5	29.5	—	3.98
BM14B(0.8)-50DS-0.4V(52)	24	11.5	10.58	12.7	25.5	29.5	—	3.98

- 7. PER REEL 8000 CONNECTORS.
- 8. THE DIMENSIONS IN PARENTHESSES ARE FOR REFERENCE.
- 9 REFER TO JIS C 0806(PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)
- 10 EMBOSSED CARRIER TAPE USED ON 10 TO 60 POSITIONS HAS THE SPROCKET HOLE ON ONE SIDE.
- 11 AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET, AND TAPE DOWN AT THE END THE COLLAR.

HRS	DRAWING NO.	EDC3-322327-01	
	PART NO.	BM14B(0.8)-*DS-0.4V(52)	
	CODE NO.	CL684	3/3